Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) DIPs

description

These devices contain four independent 2-input OR gates. They perform the Boolean functions Y = A + B or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

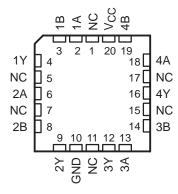
The SN54F32 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74F32 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
Н	Χ	Н
Х	Н	Н
L	L	L

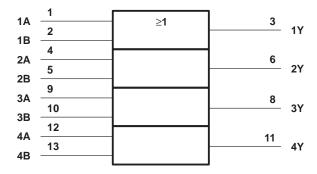
SN54F32...J PACKAGE SN74F32...D OR N PACKAGE (TOP VIEW) V_{CC} 1A 1B 4B 13 1Y 12 4A 2A ∏ 4Y 11 2B 5 10 3B 2Y 3A 9 **GND** 3Y 8

SN54F32 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram, each gate (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	-1.2 V to 7 V
Input current range	-30 mA to 5 mA
Voltage range applied to any output in the high state	. -0.5 V to V _{CC}
Current into any output in the low state	
Package thermal impedance, θ _{JA} (see Note 2): D package	127°C/W
N package	78°C/W
Storage temperature range, T _{stg}	−65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions (see Note 3)

		SN54F32		SN74F32			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
٧ _{IH}	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
lik	Input clamp current			-18			-18	mA
IOH	High-level output current			-1			-1	mA
loL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST		SN54F32			SN74F32				
PARAMETER	IES	TEST CONDITIONS			MAX	MIN	TYP‡	MAX	UNIT	
V_{IK}	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
Vo.,	$V_{CC} = 4.5 V,$	$I_{OH} = -1 \text{ mA}$	2.5	3.4		2.5	3.4		V	
VOH	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -1 \text{ mA}$				2.7			V	
V _{OL}	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.3	0.5		0.3	0.5	V	
lį	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA	
lіН	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ	
I _{IL}	$V_{CC} = 5.5 V,$	V _I = 0.5 V			-0.6			-0.6	mA	
los§	$V_{CC} = 5.5 \text{ V},$	V _O = 0	-60		-150	-60		-150	mA	
^I CCH [¶]	V _{CC} = 5.5 V			6.1	9.2		6.1	9.2	mA	
lccr	V _{CC} = 5.5 V,	V _I = 0		10.3	15.5		10.3	15.5	mA	

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

[¶]ICCH is measured with one input per gate at 4.5 V and all others grounded.

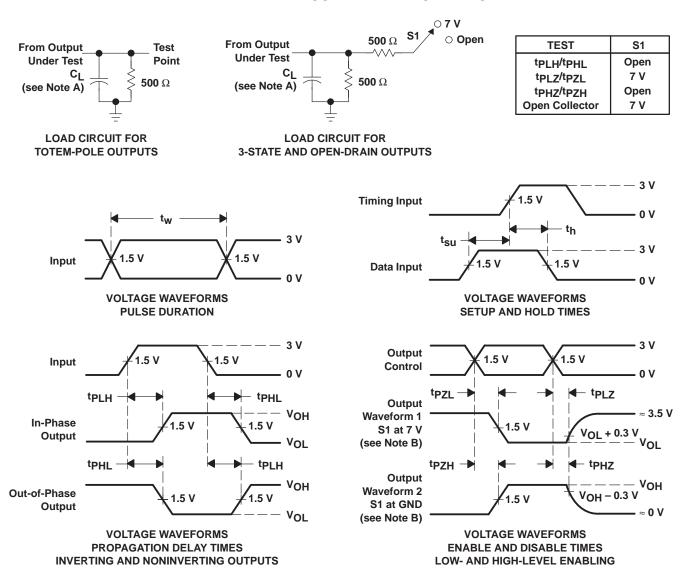
SN54F32, SN74F32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54F32		SN74F32		UNIT
	(IIVI O1)	(10017-01)		TYP	MAX	MIN	MAX	MIN	MAX	
tPLH	A or B	Y	2.2	3.8	5.6	2.2	7.5	2.2	6.6	
tpHL			2.2	3.6	5.3	1.7	7.5	2.2	6.3	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \,\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns, duty cycle = 50%.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9758801Q2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
5962-9758801QCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
5962-9758801QDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN54F32J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN74F32D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74F32DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74F32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74F32N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74F32NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54F32FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54F32J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54F32W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature

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